Model Connection Protocol extensions for Mixed Signal SiP

Taranjit Kukal (kukal@cadence.com)
Dr. Wenliang Dai (wldai@cadence.com)
Brad Brim (bradb@sigrity.com)
assisted by Eiji Fujine Fujitsu VLSI Limited

Presented by: Kevin Liu – Cadence

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Agenda

- **Why Model Connection Protocol**
- **Model Connection Protocol overview**
- **Extensions required for Mixed Signal SiP**
- **MCP Applications**
- **Summary**

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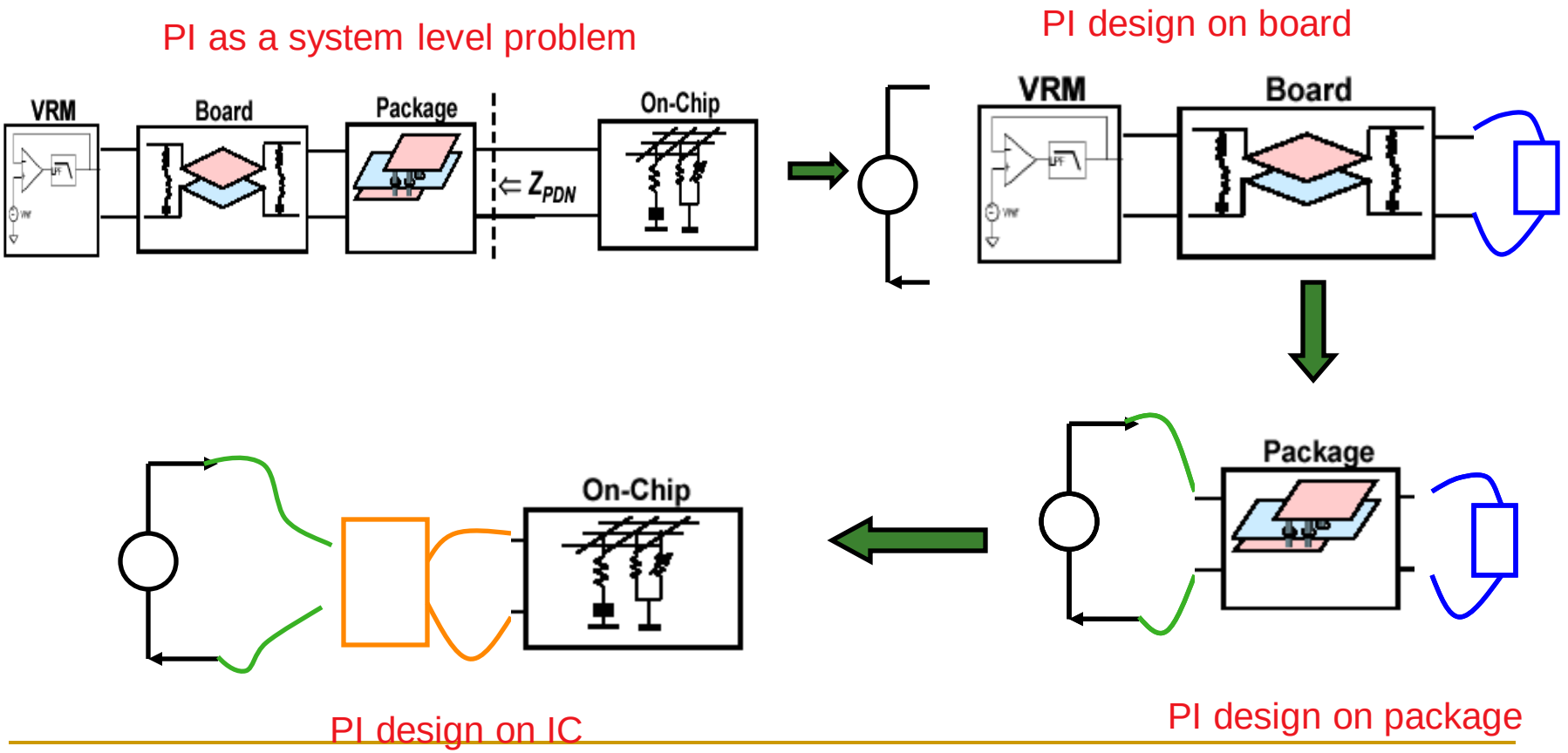
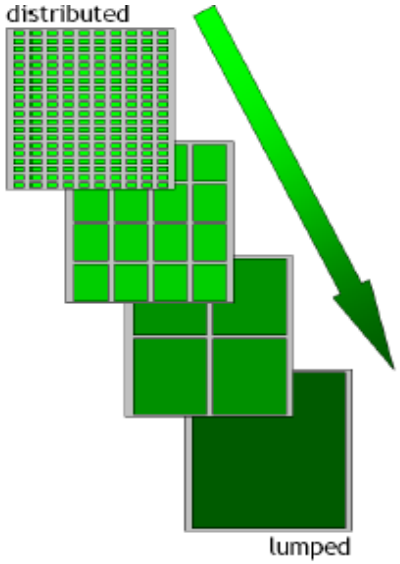
Why Model Connection Protocol - IC/Pkg/Board PDN Co-design

- Design low impedance path: supply to chip

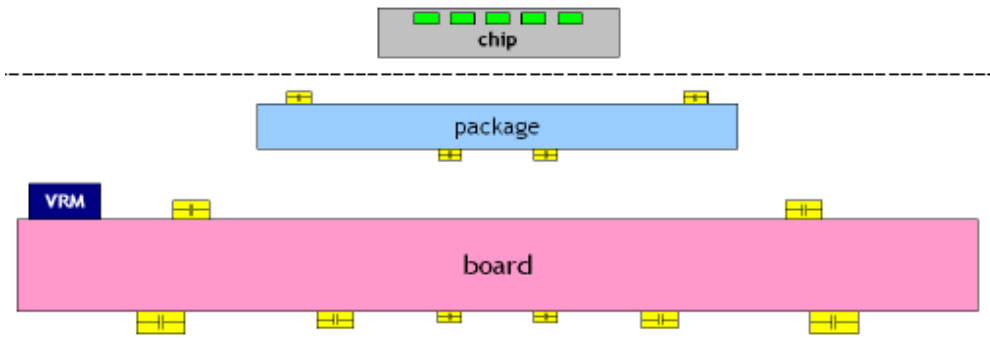


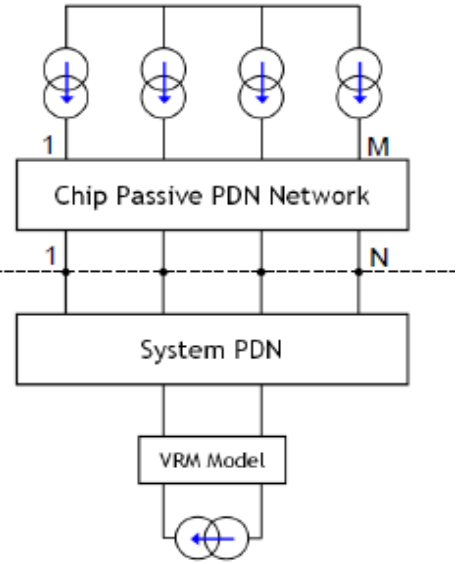
Why Model Connection Protocol - IC/Pkg/Board PDN Co-design



Chip PDN models can vary from 2-node to N-nodes, where N is the number of physical pins.

There can be 1 to M current sources, where M may be much larger than N.



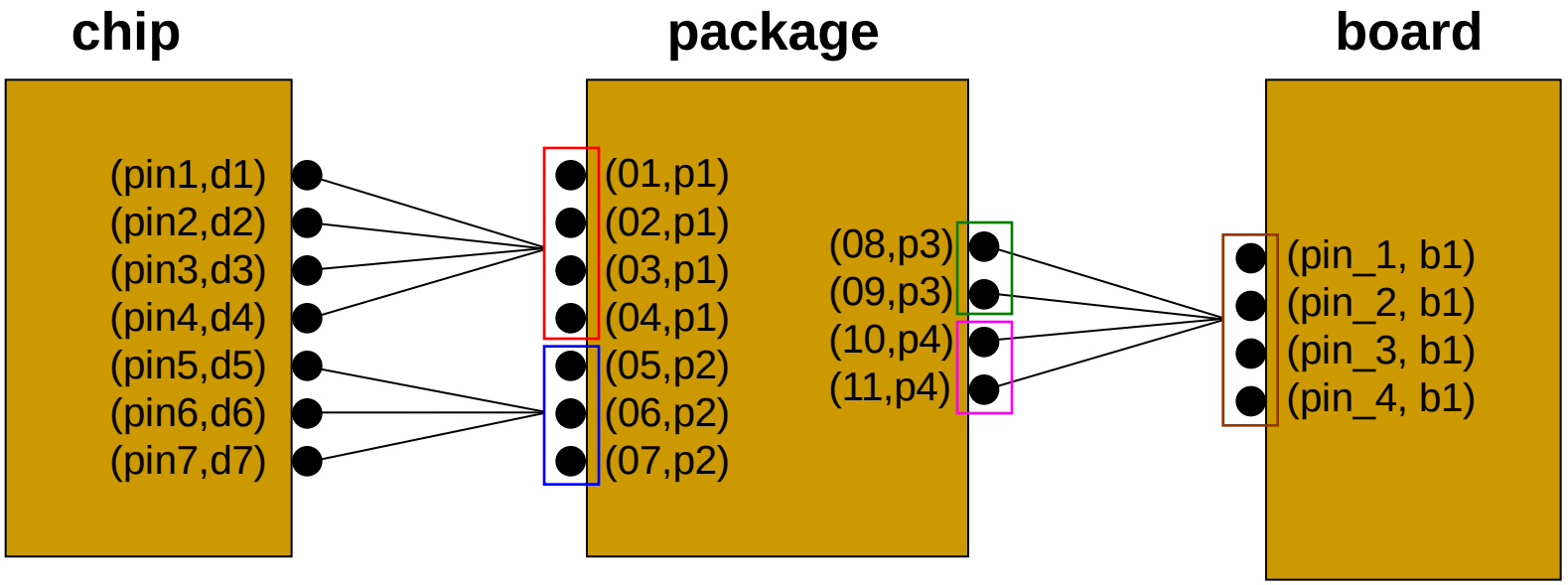


Why Model Connection Protocol - IC/Pkg/Board PDN Co-design

- Chip/Package/Board have many physical connections
  - Chip-Package Boundary:100-6000
  - Package-Board Boundary: 100-3000
- Not all electrical nodes can have per-pin resolution
  - Models may become too large for computation, simulation
- Need way to group pins and auto-connect models across IC/Pkg/Board

MCP Overview
- Establish mapping

- Pin grouping and mapping
  - **physical pin (of layout) to electrical node (of model) per Net**
  - **Mapping to connecting structure using physical location**



Example of VDD net across chip-pkg-board

MCP Overview
- Establish mapping

Pins of net

Electrical node

Netname

X-Y loc of pin

```
.subckt chip  d1 d2 d3 d4 d5 d6 d7
* [MCP Begin]
* [MCP Ver] 1.1
* [Structure Type] DIE
* [MCP Source] chip extraction tool
* [Coordinate Unit] um
* [Connection] pkg1  pkg_bumps  7
*   [Connection Type] PKG
*     [Power Nets]
*       pin1  d1  VDD    0    0
*       pin2  d2  VDD    0  100
*       pin3  d3  VDD  100    0
*       pin4  d4  VDD  100  100
*       pin5  d5  VDD   50    0
*       pin6  d6  VDD   50   50
*       pin7  d7  VDD   50  100
* [MCP End]
 --- SPICE elements ---
.ends
```

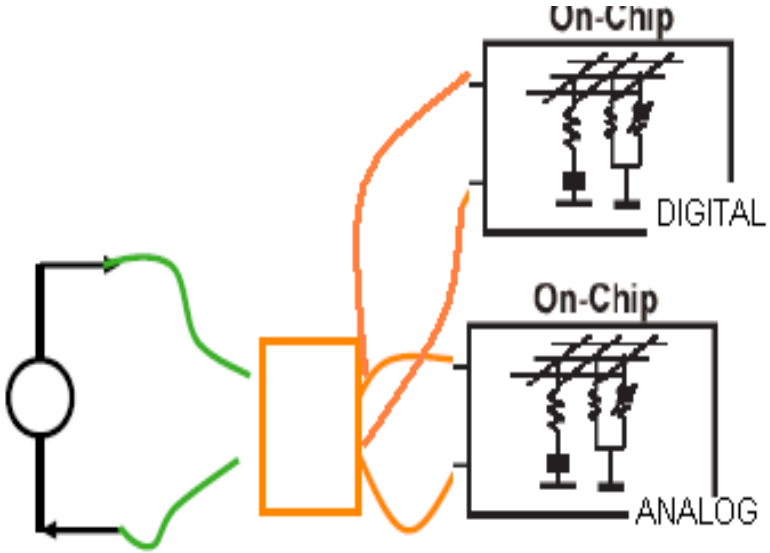
```
.subckt package  p1 p2 p3 p4
* [MCP Begin]
* [MCP Ver] 1.1
* [Structure Type] PKG
* [MCP Source] package extraction tool
* [Coordinate Unit] um
* [Connection] die1  myCPU  7
*   [Connection Type] DIE
*     [Power Nets]
*       01  p1  VDD    0    0
*       02  p1  VDD    0  100
*       03  p1  VDD  100    0
*       04  p1  VDD  100  100
*       05  p2  VDD   50    0
*       06  p2  VDD   50   50
*       07  p2  VDD   50  100
* [Connection] board1  my_board  4
*   [Connection Type] PCB
*     [Power Nets]
*       08  p3  VDD    0    0
*       09  p3  VDD    0  200
*       10  p4  VDD  200    0
*       11  p4  VDD  200  200
* [MCP End]
 --- SPICE elements ---
.ends
```

```
.subckt board  b1
* [MCP Begin]
* [MCP Ver] 1.1
* [Structure Type] PCB
* [MCP Source] board extraction tool
* [Coordinate Unit] mm
* [Connection] pkg1  pkg_balls  4
*   [Connection Type] PKG
*     [Power Nets]
*       pin_1  b1  VDD  0.0  0.0
*       pin_2  b1  VDD  0.0  0.2
*       pin_3  b1  VDD  0.2  0.0
*       pin_4  b1  VDD  0.2  0.2
* [MCP End]
 --- SPICE elements ---
.ends
```

Example of VDD net across chip-pkg-board

MCP Extensions for Mixed Signal SiP

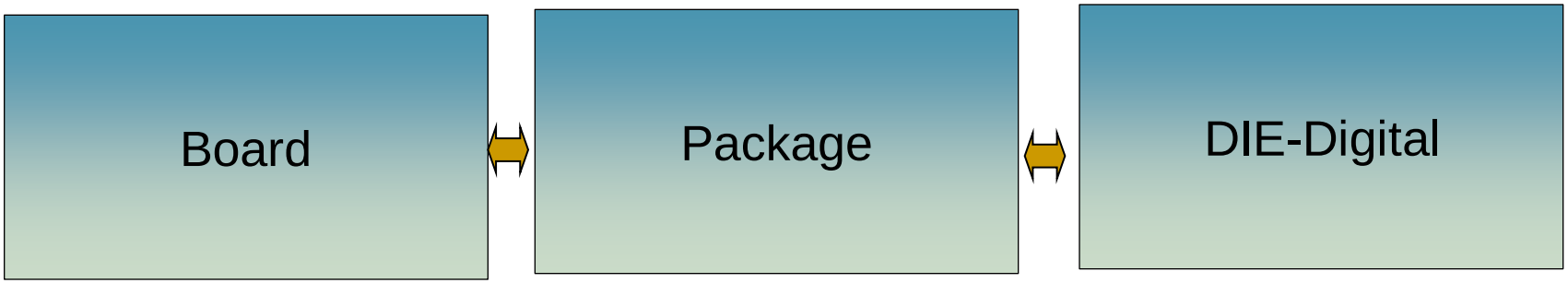
- Analyze power-delivery to ICs when Package rails supply power to
  - different ICs that could be digital and/or analog
  - RF-modules and Passive/Active SMDs
- Need Schematic driven Mixed Signal Simulations to process IR-drop at power-rails



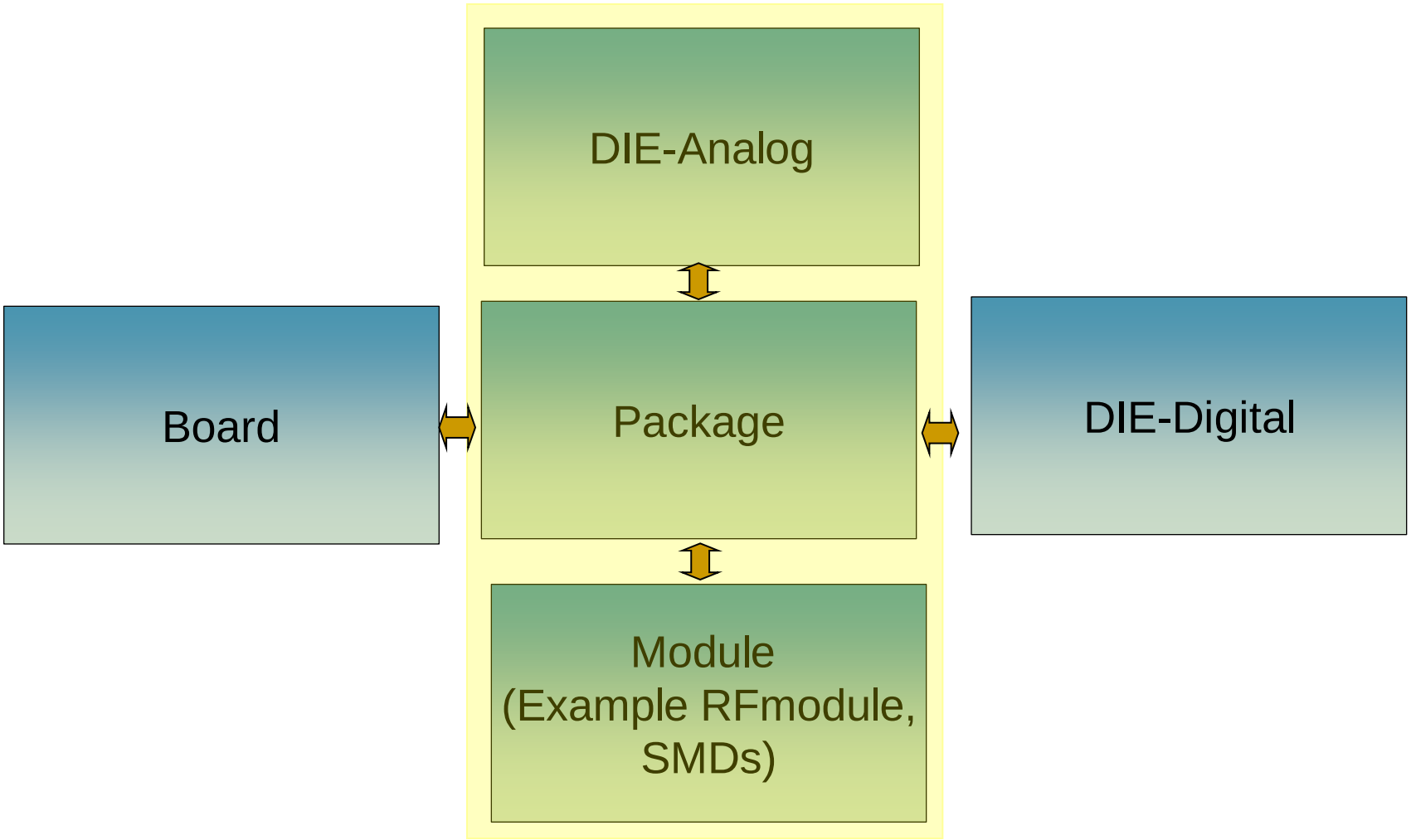
PDN supplying Analog and Digital multi-DIE system

MCP Extensions for Mixed Signal SiP

-Current MCP scope

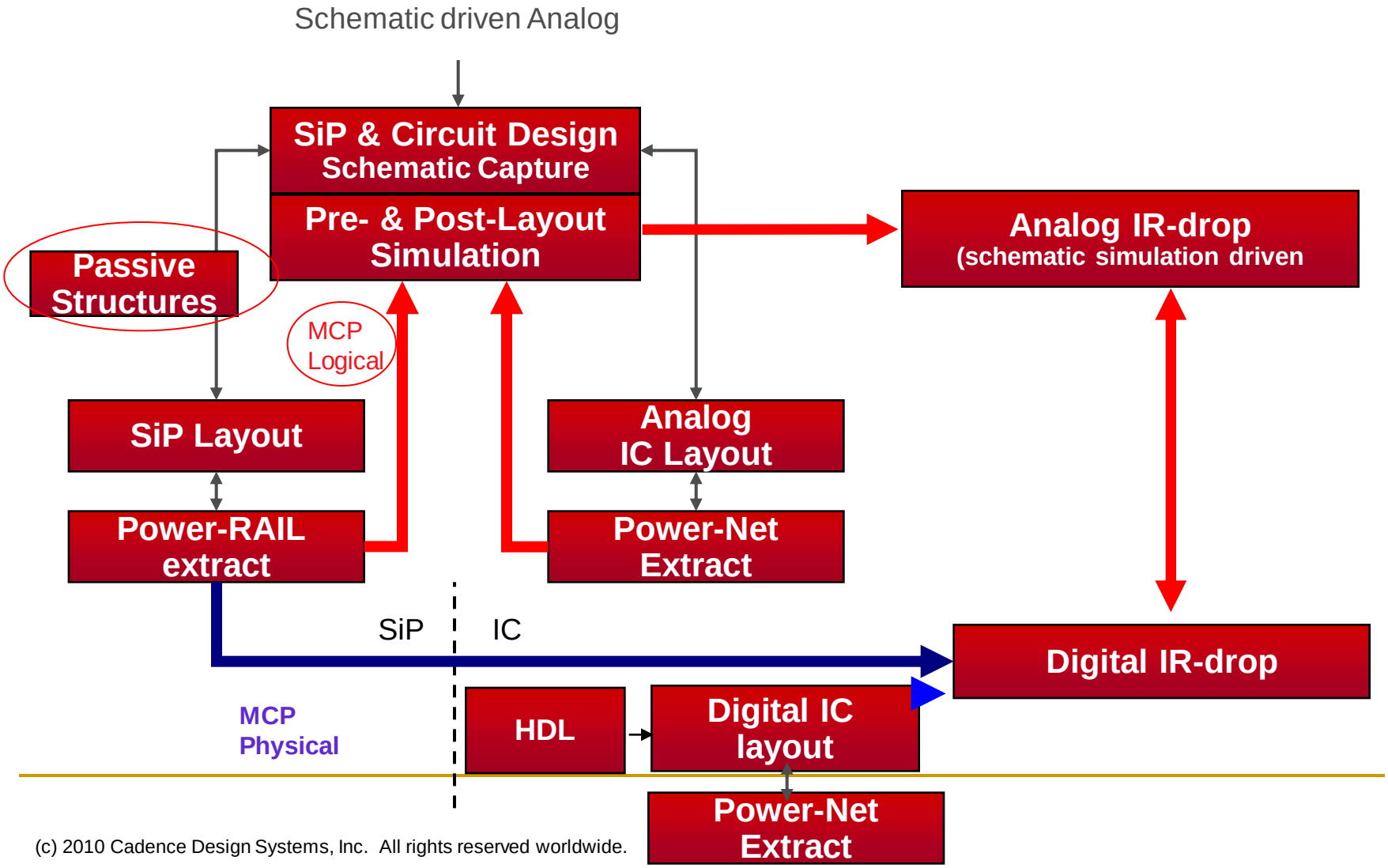


MCP Extensions for Mixed Signal SiP



MCP Extensions for Mixed Signal SiP

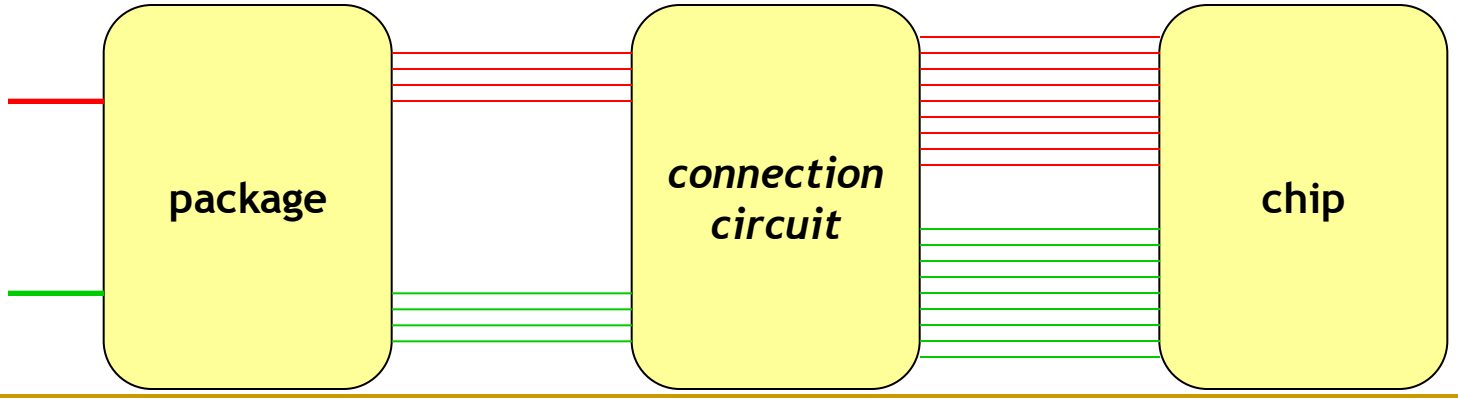
- Mixed Signal IR-drop Task Flow



MCP Extensions for Mixed Signal SiP

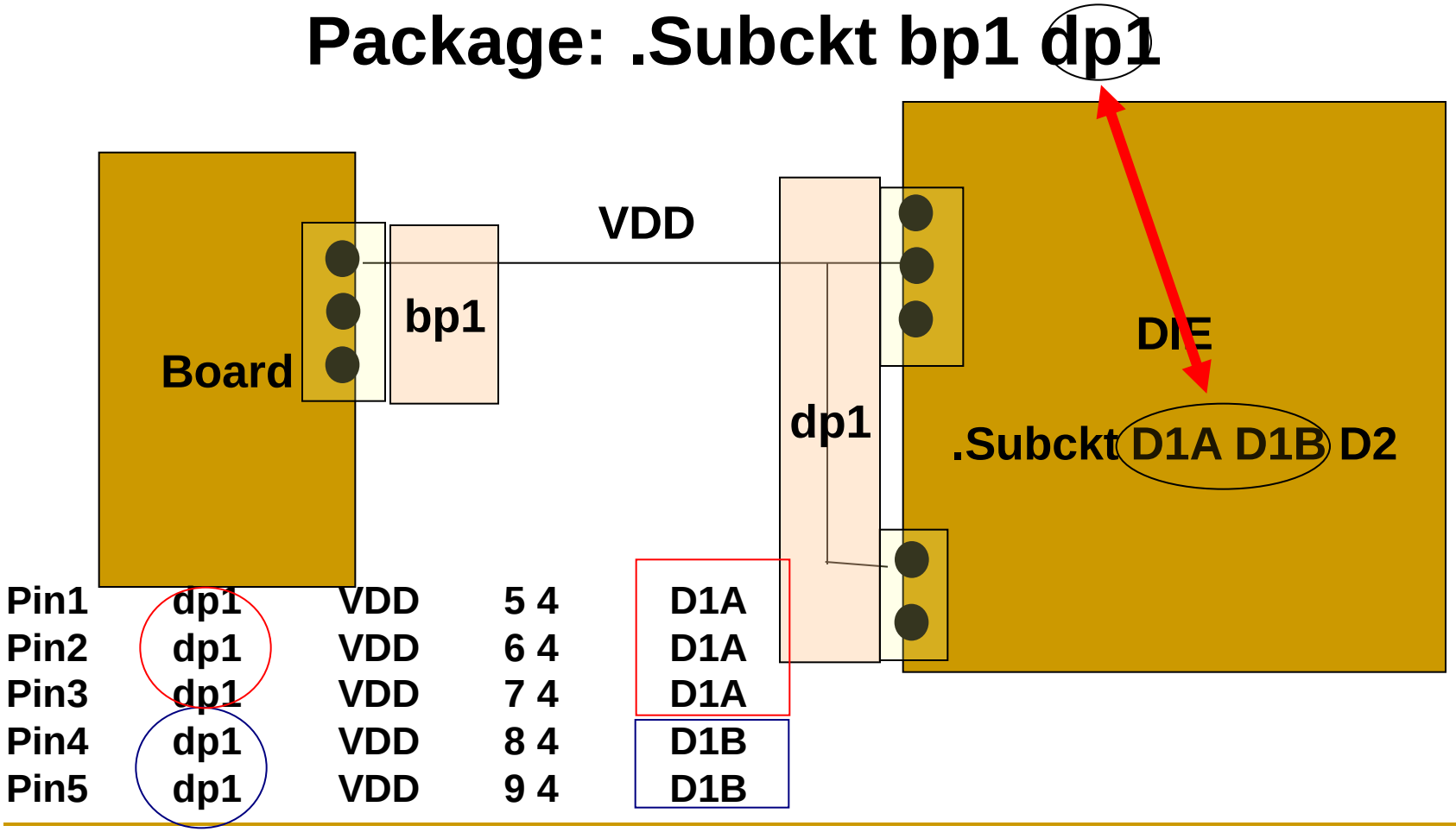
- Electrical connectivity of models with disparate pin grouping

- Support for mapping of different electrical port-groups across different structures
  - As an example
    - a package model with 2-by-2 grid-based pin grouping
    - a chip model with 3-by-3 grid-based pin grouping
  - desired is an electrical circuit to interface between an 8 node circuit and an 18 node circuit



MCP Extensions for Mixed Signal SiP

- Optional Column for mapping of electrical nodes across structures

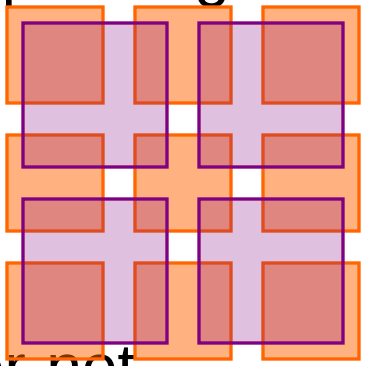


MCP Extensions for Mixed Signal SiP

- Caution: Electrical connectivity with disparate pin grouping

- Examine the nodes of the each net
  - for overlapping pin group domains, the corresponding nodes are shorted together
    - (1,1) node shorts together {(1,1), (1,2), (2,1), (2,2)} nodes
    - (1,2) node shorts together {(1,2), (1,3), (2,2), (2,3)} nodes
    - (2,1) node shorts together {(2,1), (2,2), (3,1), (3,2)} nodes
    - (2,2) node shorts together {(2,2), (2,3), (3,2), (3,3)} nodes

    alternately
    - (2,2) node shorts together {(1,1), (1,2), (2,1), (2,2)} nodes
  - all nodes are shorted together, reducing to per-net connectivity
    - instead of 8 or 18 node electrical connectivity it is actually 2 node connectivity



- Recommendation
  - Connecting two disparately pin-grouped models is possible by choosing to short together electrical nodes that have overlapping pin domains
    - but it can reduce the effective resolution of the model at the chip/package interface
    - Useful in case of early debugging and quick connectivity

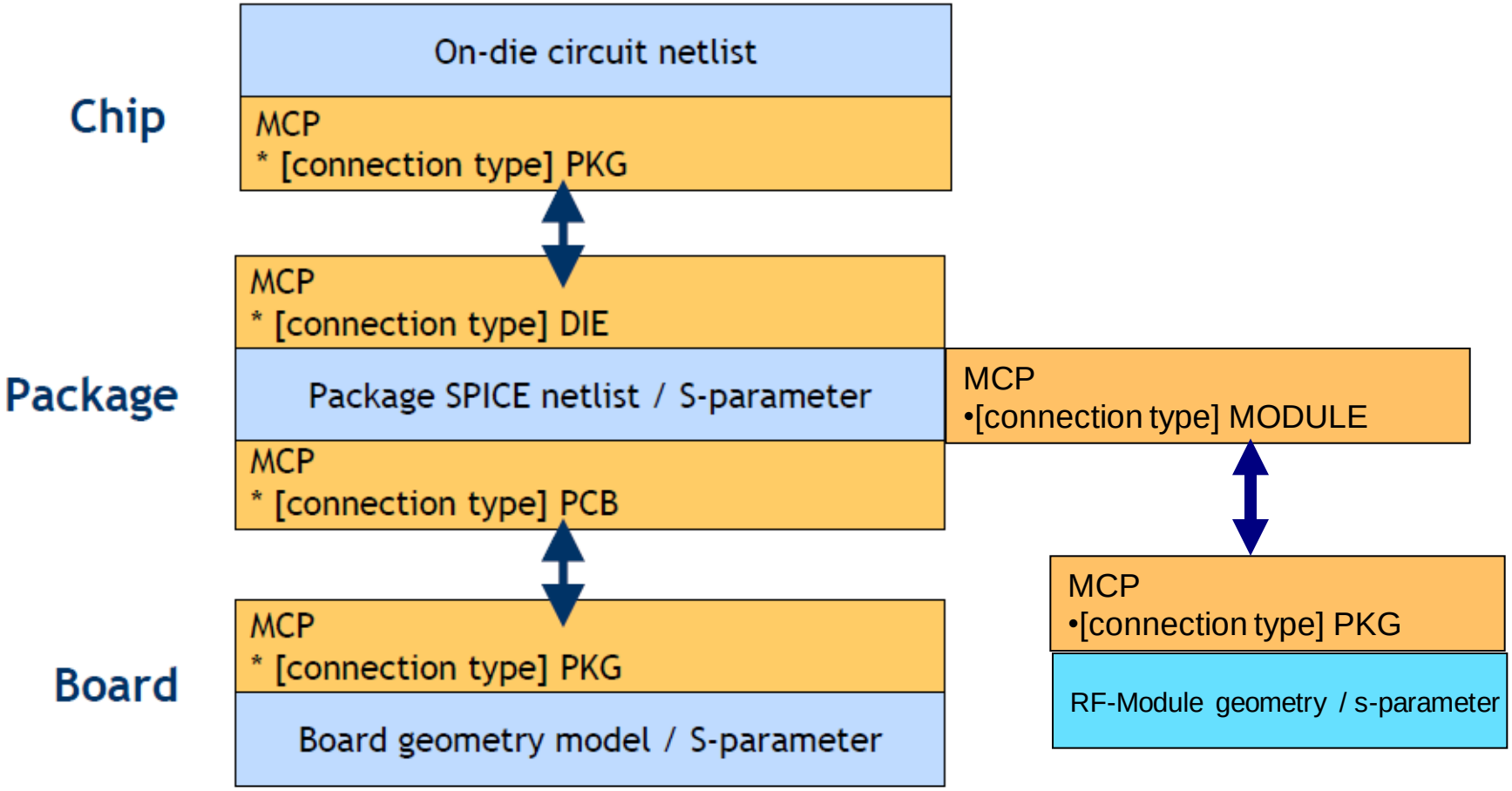
Extensions over existing MCP

- Support for Modules as connect type structures

- Mixed Signal SiPs would have elements other that ICs like
  - RFmodules
  - Metal Passive structures
  - SMD components
  - Silicon Interposers
- These structure draw power impacting PDN loading and hence we need to support [Module] category besides IC, Package and Board

Extensions over existing MCP

- Support for Modules as connect type structures



Extensions over existing MCP

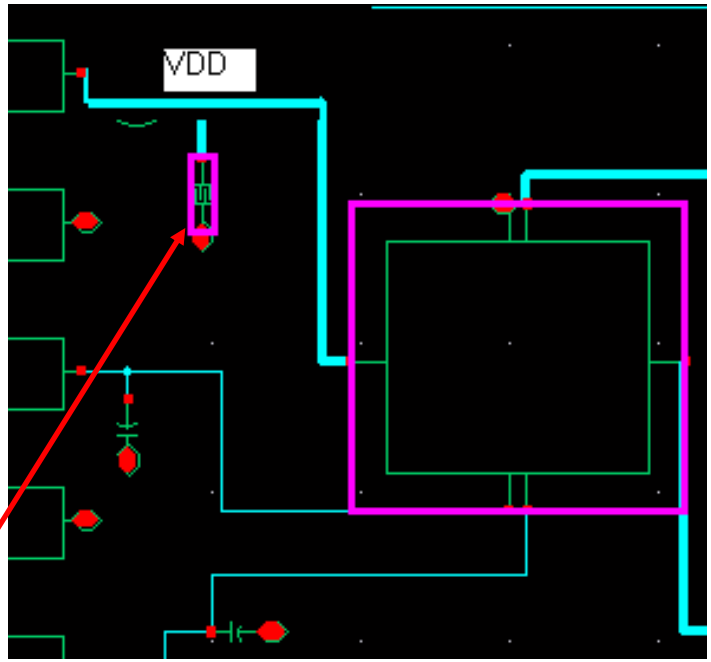
- Connection by Refdes besides X-Y location

- In order to connect to structures that are SMD or metal-passive structures on SiP – usually a case for Mixed Signal SiP, it becomes difficult to connect by X-Y locations.
- Early analysis may require quick way of stitching the models across structures and minor placement or resolution changes can cause X-Y mapping to fail.
- Optional column showing connection by REFDES makes easy mapping for Mixed-Signal modules and early trials
  - Examples of connecting interfaces could be
    - IO-cellname (DIE IO)
    - R1:1 (pin 1 of R1)
    - CONN:1 (pin1 of PCB connector)
    - my_model_opamp:3 (port-3 of opamp subcircuit)

Extensions over existing MCP

- Connection by Refdes besides X-Y location

- Simulating Analog DIE in package schematics with loading from passive structures connected to DIE
- The simulation data is post-processed to obtain IR-drop at power-rails



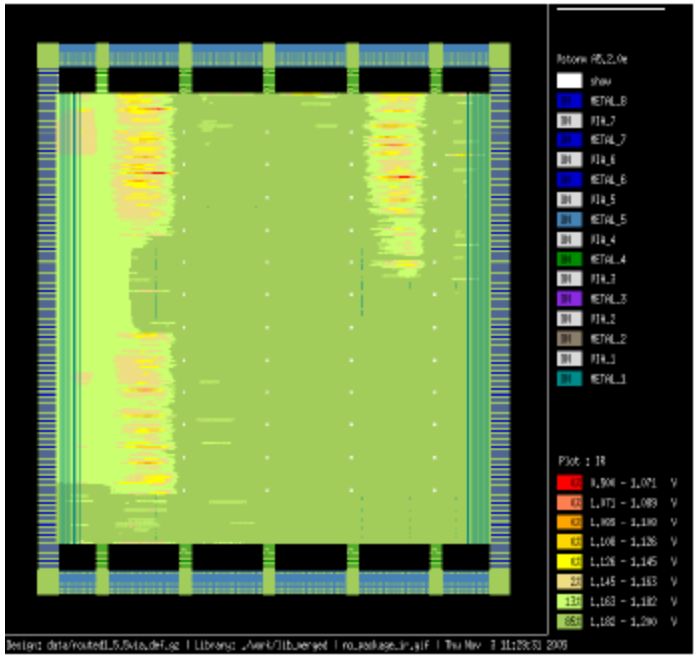
[connection type MODULE]

Pin1	**dp1**	**VDD**	**5 4**	**varistor1:2 //Reference_design:pin//**
Pin2	**dp1**	**VDD**	**6 4**	**varistor2:2**
Pin3	**dp1**	**VDD**	**7 4**	

MCP applications: Digital DIE IR-drop

- Digital DIE in context of package model

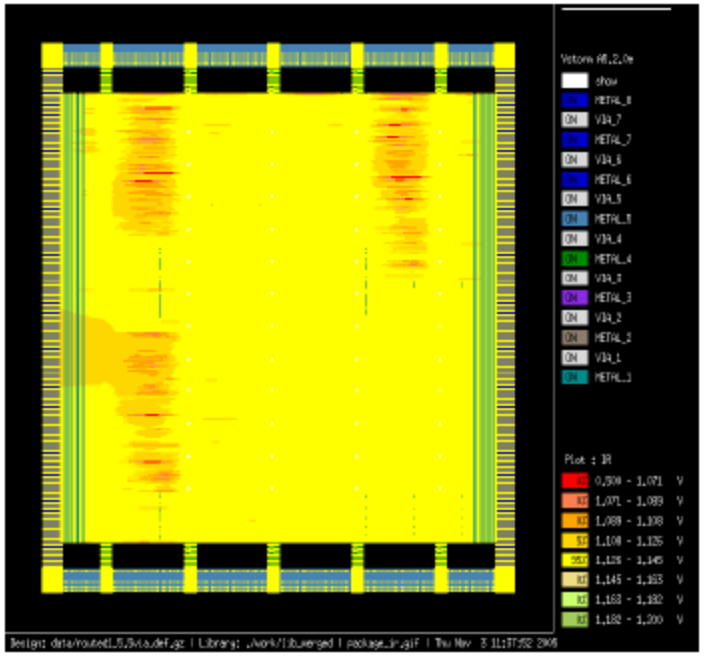
Simulation results of Vdd rail: Dynamic IR-Drop



Without package effects

worst-case IR drop :

147.5mV



With package effects

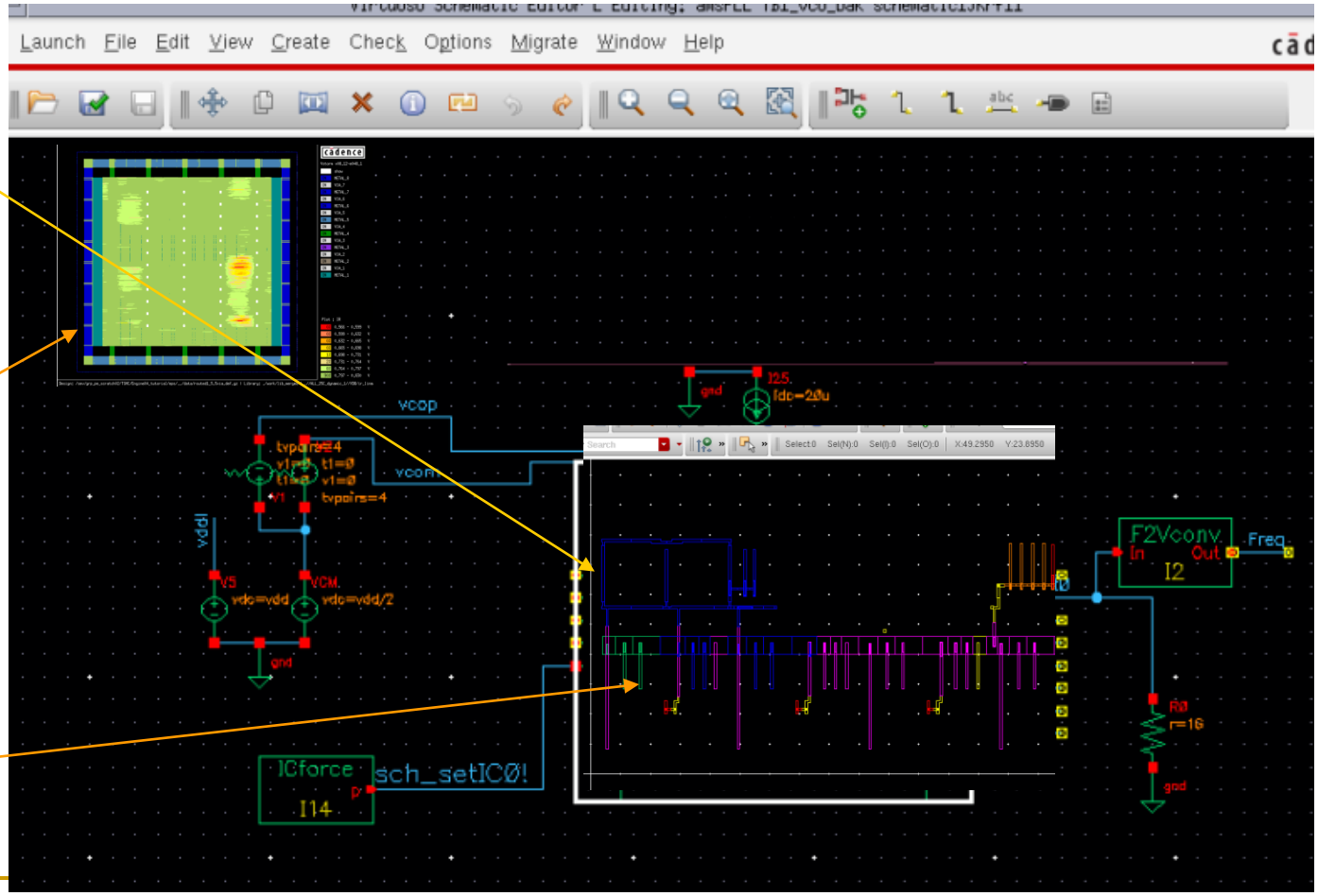
worst-case IR drop :

179.3mV

MCP applications: Analog DIE IR-drop

-Analog DIE in context of package model & Digital DIE-models

- Analog DIE test-bench with power-rail model
- Digital DIE model connected to represent loading of power-rail
- Analog DIE IR-drop post simulations



Summary: MCP format updated in context of Mixed Signal contents

```
* [MCP Begin]
* [MCP Ver] 1.1
* [Structure Type] {DIE|PKG|PCB}
* [MCP Source] source text
* [Coordinate Unit] unit
* [Connection] connectionName partName numberPhysicalPins
*   [Connection Type] {DIE|PKG|PCB}
*       [Power Nets]
*         pinName  modelNodeName  netName  x  y
*         …
*         pinName  modelNodeName  netName  x  y
*       [Ground Nets]
*         pinName  modelNodeName  netName  x  y
*         …
*         pinName  modelNodeName  netName  x  y
*       [Signal Nets]
*         pinName  modelNodeName  netName  x  y
*         …
*         pinName  modelNodeName  netName  x  y
* [MCP End]
```

Device Info (self)

Device Info (external)

Module

Connection Info

Pin Info

I/F electrical node column

I/F part-ref column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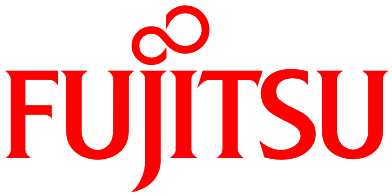
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